# Low Forward Voltage, Low Leakage Trench-based **Schottky Rectifier**

#### Features

- Fine Lithography Trench–based Schottky Technology for Very Low Forward Voltage and Low Leakage
- Fast Switching with Exceptional Temperature Stability
- Low Power Loss and Lower Operating Temperature
- Higher Efficiency for Achieving Regulatory Compliance
- High Surge Capability
- NRV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb–Free and Halide–Free Devices

## **Typical Applications**

- Switching Power Supplies including Wireless, Smartphone and Notebook Adapters
- High Frequency and DC–DC Converters
- Freewheeling and OR-ing diodes
- Reverse Battery Protection
- Instrumentation
- LED Lighting

## **Mechanical Characteristics:**

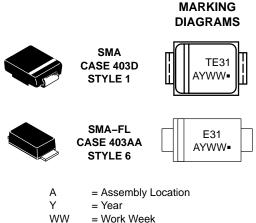
- Case: Epoxy, Molded
- Epoxy Meets Flammability Rating UL 94–0 @ 0.125 in.
- Lead Finish: 100% Matte Sn (Tin)
- Lead and Mounting SurfaceTemperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL 1 Requirements



## **ON Semiconductor®**

www.onsemi.com





= Work Week

= Pb-Free Package (Note: Microdot may be in either location)

## **ORDERING INFORMATION**

Device	Package	Shipping†
NRVTSA3100ET3G	SMA (Pb–Free)	5000 / Tape & Reel
NRVTSAF3100ET3G	SMA-FL (Pb-Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	100	V	
Average Rectified Forward Current $(T_L = 134^{\circ}C)$	I <sub>F(AV)</sub>	3.0	A	
Peak Repetitive Forward Current, (Square Wave, 20 kHz, T <sub>L</sub> = 127°C)	I <sub>FRM</sub>	6.0	A	
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I <sub>FSM</sub>	50	A	
Storage Temperature Range	T <sub>stg</sub>	-65 to +175	°C	
Operating Junction Temperature	TJ	-55 to +175	°C	
ESD Rating (Human Body Model)		1A		
ESD Rating (Machine Model)		M3		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

Characteristic		Symbol	Тур	Max	Unit
Maximum Thermal Resistance, Steady State (Note 1)					°C/W
NRVTSA3100E	Junction-to-Lead	$R_{\theta JL}$	-	22	
	Junction-to-Ambient	R <sub>0JA</sub>	-	80	
NRVTSAF3100E	Junction-to-Lead	R <sub>0JL</sub>	-	23.8	
	Junction-to-Ambient	$R_{\thetaJA}$	-	82	

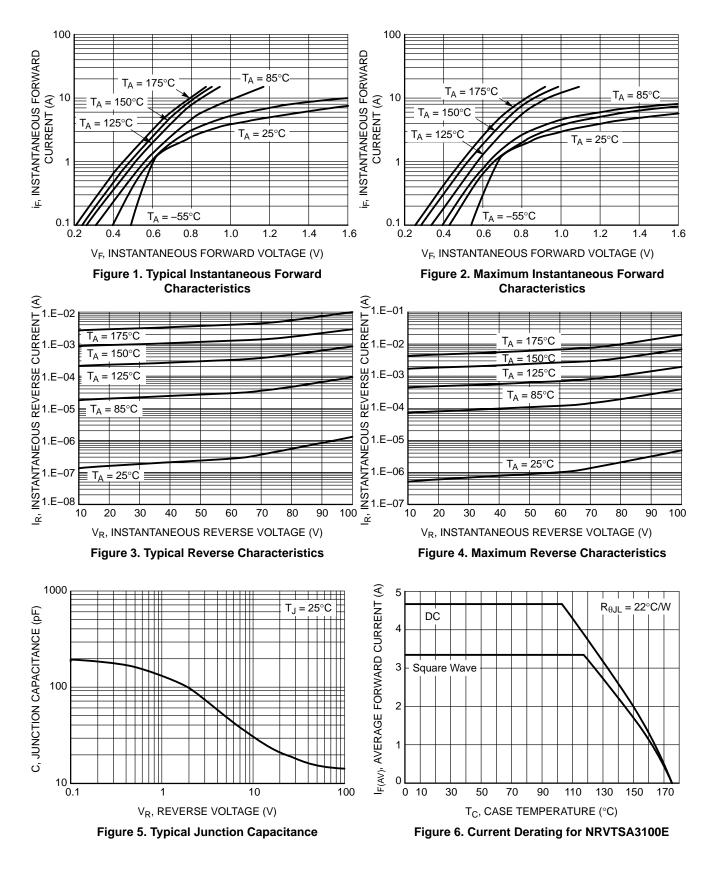
#### **ELECTRICAL CHARACTERISTICS**

Instantaneous Forward Voltage (Note 2)	۷ <sub>F</sub>			V
$(i_{F} = 1.0 \text{ Amps}, T_{J} = 25^{\circ}\text{C})$		0.61	-	
$(i_F = 3.0 \text{ Amps}, T_J = 25^{\circ}C)$		0.88	0.995	
(i <sub>F</sub> = 1.0 Amps, T <sub>J</sub> = 125°C)		0.53	_	
$(i_F = 3.0 \text{ Amps}, T_J = 125^{\circ}\text{C})$		0.66	0.70	
Reverse Current (Note 2)	i <sub>R</sub>			
(Rated dc Voltage, $T_J = 25^{\circ}C$ )		0.90	5.0	μΑ
(Rated dc Voltage, $T_J = 125^{\circ}C$ )		0.62	2.0	mA
Diode Capacitance	C <sub>d</sub>			pF
(Rated dc Voltage, $T_J = 25^{\circ}C$ , f = 1 MHz)		14.3		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 1. Assumes 600 mm<sup>2</sup> 1 oz. copper bond pad, on a FR4 board.

2. Pulse Test: Pulse Width =  $300 \ \mu s$ , Duty Cycle  $\leq 2.0\%$ .

## **TYPICAL CHARACTERISTICS**



## **TYPICAL CHARACTERISTICS**

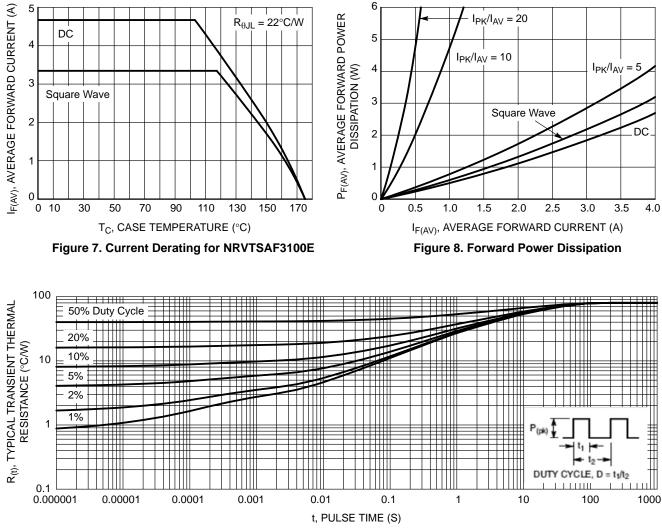
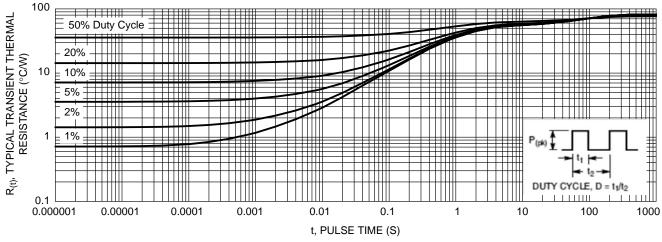


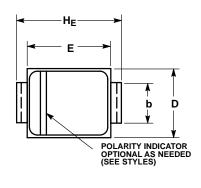
Figure 9. Typical Transient Thermal Response, Junction-to-Ambient for NRVTSA3100E





## PACKAGE DIMENSIONS

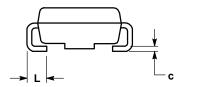
SMA CASE 403D-02 ISSUE G



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M,

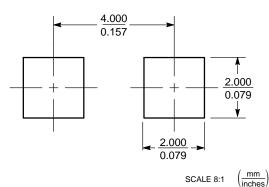
Dimensional and Poletration of Enclanding Person, 1982.
CONTROLLING DIMENSION: INCH.
DIMENSION 5 SHALL BE MEASURED WITHIN DIMENSION L.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.97	2.10	2.20	0.078	0.083	0.087
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.27	1.45	1.63	0.050	0.057	0.064
с	0.15	0.28	0.41	0.006	0.011	0.016
D	2.29	2.60	2.92	0.090	0.103	0.115
E	4.06	4.32	4.57	0.160	0.170	0.180
HE	4.83	5.21	5.59	0.190	0.205	0.220
L	0.76	1.14	1.52	0.030	0.045	0.060





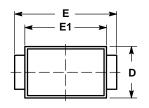
**SOLDERING FOOTPRINT\*** 



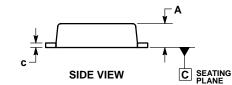
\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

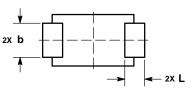
#### PACKAGE DIMENSIONS

SMA-FL CASE 403AA ISSUE O

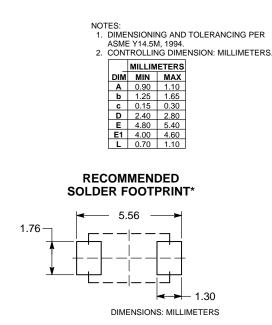








**BOTTOM VIEW** 



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdt/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all aws, regulations and safety requirements or standards, regardless of any support or applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights or the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application. Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and

#### PUBLICATION ORDERING INFORMATION

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 700 2010

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81–3–5817–1050 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative